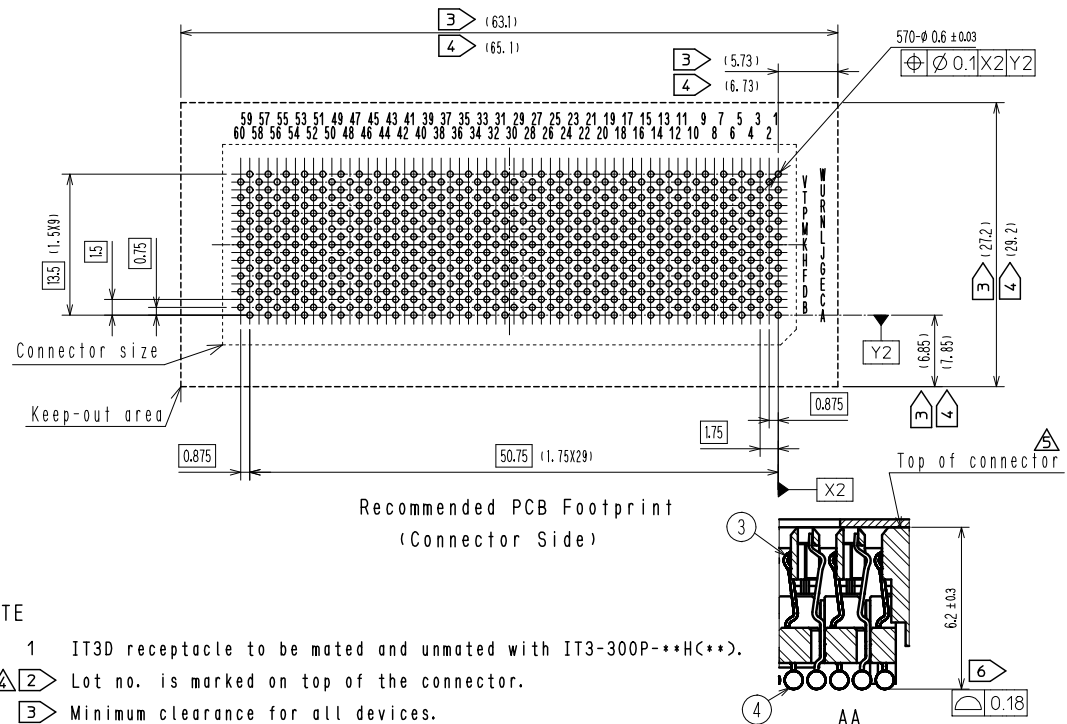
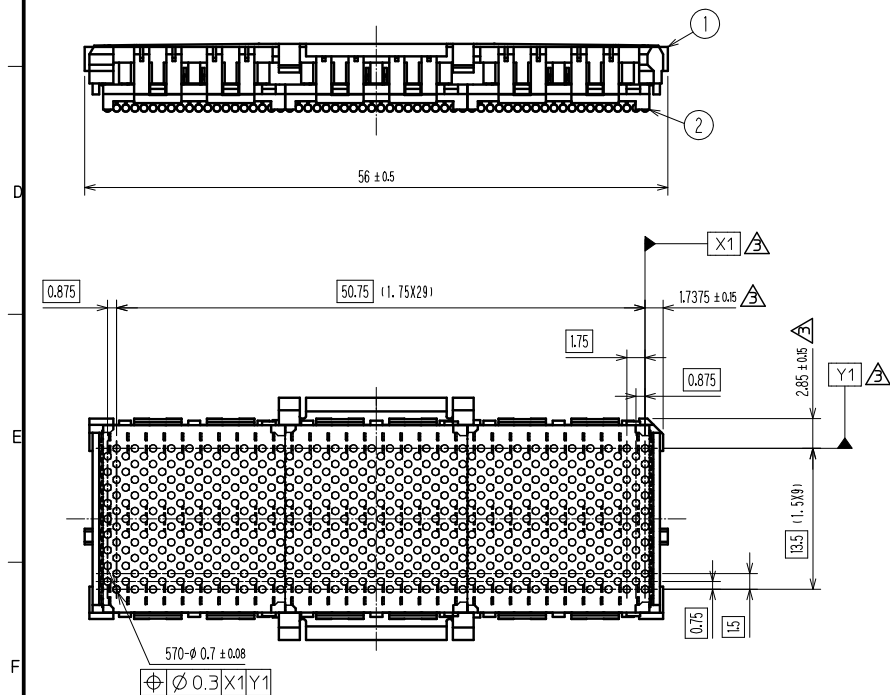
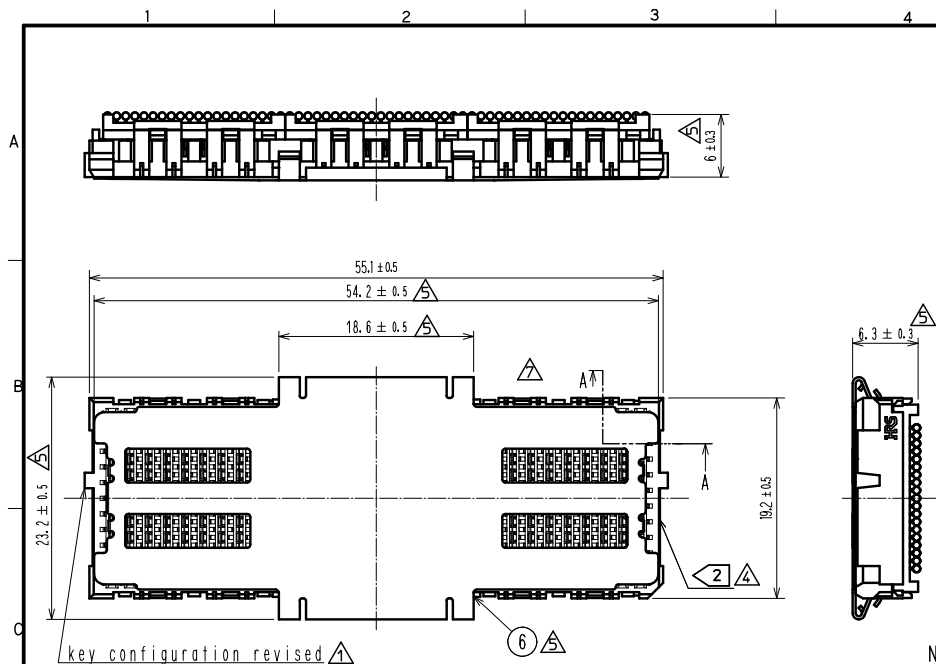




NOTE

- 1 IT3D receptacle to be mated and unmated with IT3-300P-***H(***).
- 2 Lot no. is marked on top of the connector.
- 3 Minimum clearance for all devices.
- 4 Minimum clearance for sensitive devices.
- 5 More information of this product is available in HIROSE document : ETAD-F0347 "IT3 Design Guideline".
- 6 Maximum coplanarity of the ball field is 0.18mm.
- 7 Please remove the pick up cap (part No.6) from the IT3 connector after reflow soldering.
- 8 The removed pick up cap (part No.6) should not be reused.
- 9 Standard package of 48pcs are packaged in a carton box.
- 10 This product is categorized in the MSL2A of IPC/JEDEC J-STD-020B. It is recommended to use within four weeks, defined by JEDEC, in the office environment after unpacked.
- 11 This product is a solder ball locations and co planarity sensitive BGA connector. It is recommended to handle this product with the automated machine. Solder ball locations and co planarity might be damaged accidentally when it is manually handled by assembly workers.

3	Copper alloy	Contact area : Nickel(1.5µm) + Gold(0.76µm)			6	SUS 	PICK UP CAP 		
		Other area : Nickel(1.5µm)							
2	LCP	BLACK . UL94V-0			5	HIPS	TRAY. BLACK		
1	LCP	BLACK . UL94V-0			4	TIN	Sn(96.5)-Ag(3)-Cu(0.5)		
NO.	MATERIAL	FINISH, REMARKS			NO.	MATERIAL	FINISH, REMARKS		
UNITS		SCALE	REV	COUNT	DESCRIPTION OF REVISIONS		DESIGNED	CHECKED	DATE
mm		2 : 1		1	REVISED CAP SHAPE		TS. KIKUCHI	TS. MATSUO	09.10.15
		APPROVED : T. Matsuo		07/26/2007		DRAWING NO. EDC3-157108-03			
		CHECKED : T. Matsuo		07/26/2007		PART NO. IT3D-300S-BGA(37)			
		DESIGNED : T. Takada		07/26/2007		CODE NO. CL636-0007-9-37			
		DRAWN : T. Takada		07/26/2007		 			

